





EP2600ETTS-25.000M

 <p>Lead Free COMPLIANT</p>	 <p>EU RoHS 2011/65 + 2015/863 COMPLIANT</p>	 <p>China RoHS COMPLIANT</p>	 <p>REACH SVHC 163 Jun 15, 2015 COMPLIANT</p>
--	--	--	---



ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 25.000MHz ± 100 ppm -40°C to +85°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	25.000MHz
Frequency Tolerance/Stability	± 100 ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Aging at 25°C	± 5 ppm/year Maximum
Operating Temperature Range	-40°C to +85°C
Supply Voltage	3.3Vdc $\pm 10\%$
Input Current	28mA Maximum (Unloaded)
Output Voltage Logic High (Voh)	Vdd-0.4Vdc Minimum (IOH= -8mA)
Output Voltage Logic Low (Vol)	0.4Vdc Maximum (IOL= +8mA)
Rise/Fall Time	4nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	50 ± 5 (%) (Measured at 50% of waveform)
Load Drive Capability	30pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (Disabled Output: High Impedance)
Tri-State Input Voltage (Vih and Vil)	70% of Vdd Minimum to enable output, 20% of Vdd Maximum to disable output, No Connect to enable output.
Disable Current	16mA Maximum (Pin 1 = Ground)
Absolute Clock Jitter	± 250 pSec Maximum, ± 100 pSec Typical
One Sigma Clock Period Jitter	± 50 pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

EP2600ETTTTS-25.000M [↗](#)

MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Tri-State (High Impedance)
2	Ground/Case Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	ECLIPTEK
2	25.000M
3	XXXXX XXXXX=Ecliptek Manufacturing Identifier

Suggested Solder Pad Layout

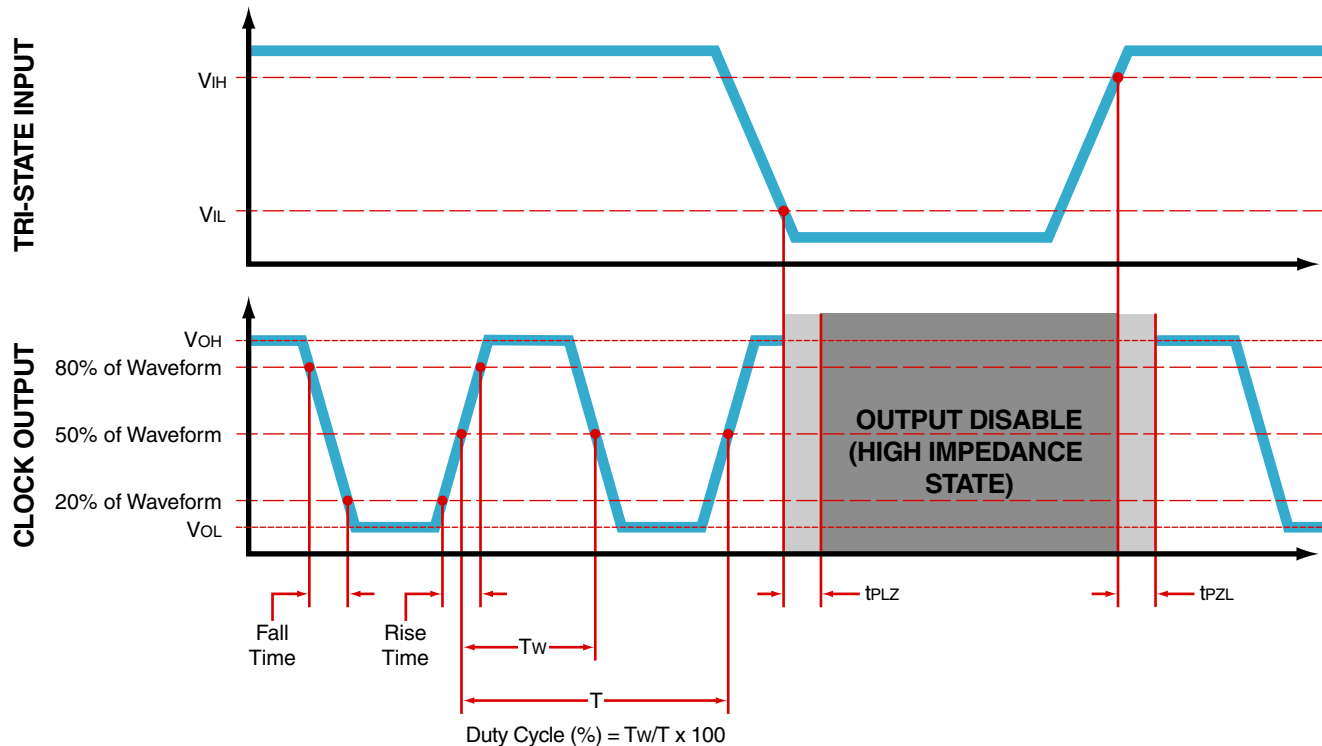
All Dimensions in Millimeters



All Tolerances are ±0.1

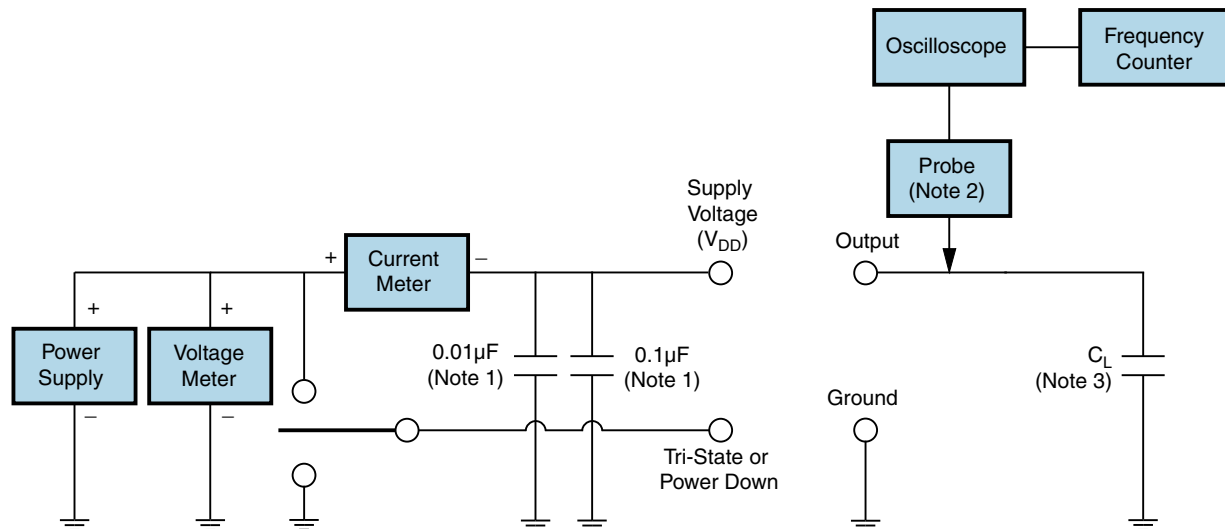
EP2600ETTTTS-25.000M [↗](#)

OUTPUT WAVEFORM & TIMING DIAGRAM



EP2600ETTS-25.000M [↗](#)

Test Circuit for CMOS Output



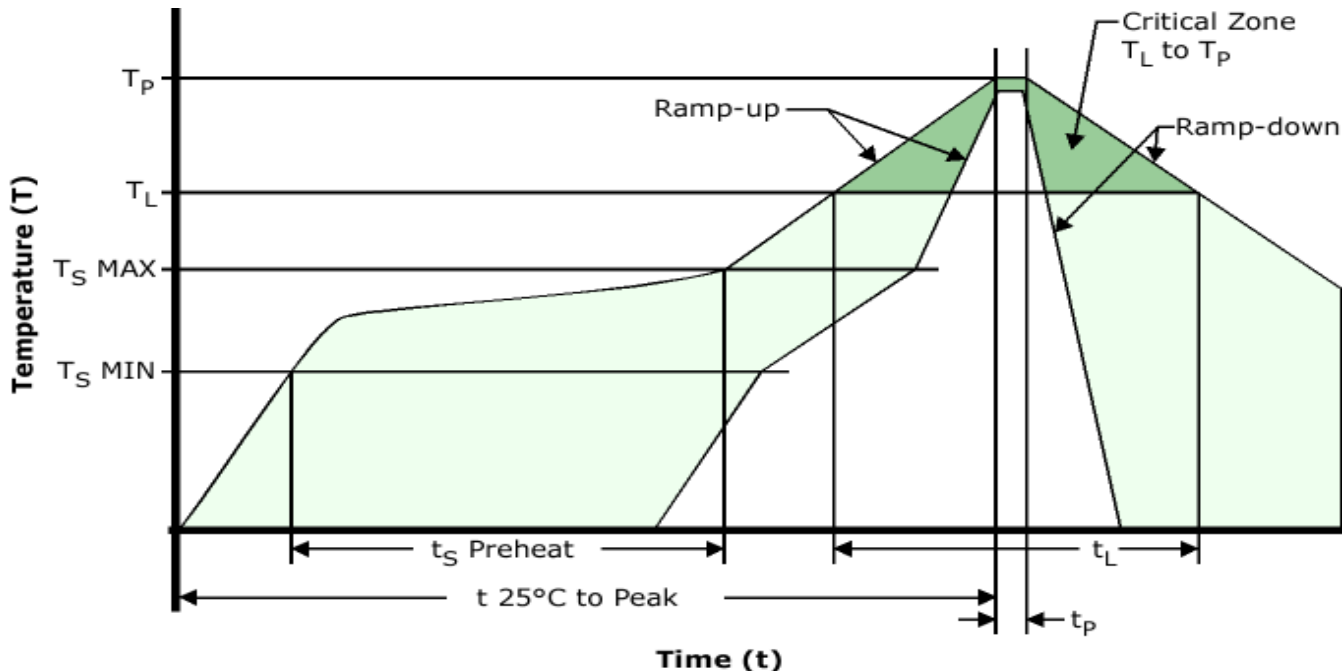
Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value CL includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

EP2600ETTS-25.000M [↗](#)

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T_S MAX to T_L (Ramp-up Rate) 3°C/Second Maximum

Preheat

- Temperature Minimum (T_S MIN) 150°C
- Temperature Typical (T_S TYP) 175°C
- Temperature Maximum (T_S MAX) 200°C
- Time (t_s MIN) 60 - 180 Seconds

Ramp-up Rate (T_L to T_P) 3°C/Second Maximum

Time Maintained Above:

- Temperature (T_L) 217°C
- Time (t_L) 60 - 150 Seconds

Peak Temperature (T_P) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature (T_P Target) 250°C +0/-5°C

Time within 5°C of actual peak (t_p) 20 - 40 Seconds

Ramp-down Rate 6°C/Second Maximum

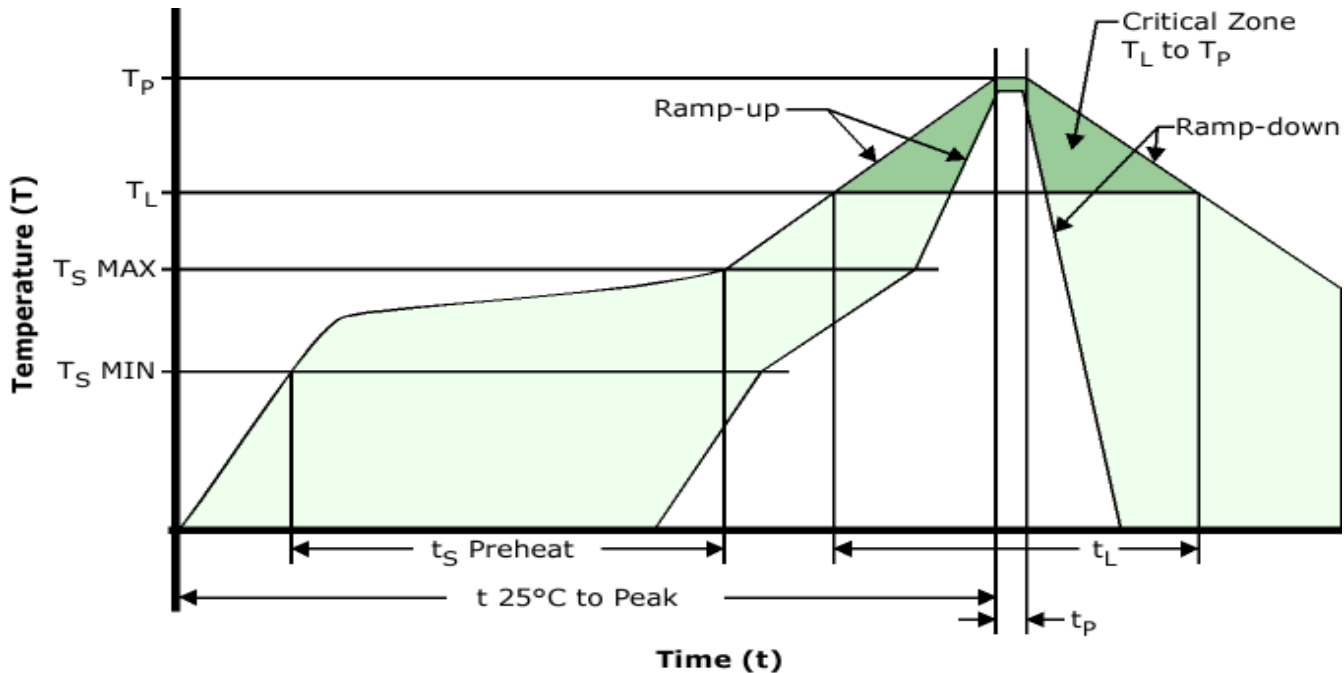
Time 25°C to Peak Temperature (t) 8 Minutes Maximum

Moisture Sensitivity Level Level 1

Additional Notes Temperatures shown are applied to body of device.

EP2600ETTS-25.000M [↗](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate) 5°C/Second Maximum

Preheat

- Temperature Minimum (Ts MIN) N/A
 - Temperature Typical (Ts TYP) 150°C
 - Temperature Maximum (Ts MAX) N/A
 - Time (ts MIN) 60 - 120 Seconds

Ramp-up Rate (TL to TP) 5°C/Second Maximum

Time Maintained Above:

- Temperature (TL) 150°C
 - Time (tL) 200 Seconds Maximum

Peak Temperature (TP) 240°C Maximum

Target Peak Temperature (TP Target) 240°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (tp) 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

Ramp-down Rate 5°C/Second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Additional Notes Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Ecliptek:](#)

[EP2600ETTTS-25.000M](#)



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.